



US00D356067S

United States Patent [19]

[11] Patent Number: **Des. 356,067**

Itoh

[45] Date of Patent: **** Mar. 7, 1995**

[54] **HEAT DISSIPATING DEVICE FOR A SEMICONDUCTOR PACKAGE**

[75] Inventor: **Akira Itoh, Osaka, Japan**

[73] Assignee: **Itoh Research & Development Laboratory Co., Ltd., Osaka, Japan**

[**] Term: **14 Years**

[21] Appl. No.: **933,532**

[22] Filed: **Aug. 21, 1992**

[30] **Foreign Application Priority Data**

Mar. 4, 1992 [JP] Japan 4-6203

[52] U.S. Cl. **D13/179**

[58] Field of Search D13/179, 182; 437/902; 165/80.2, 80.3, 104.33; 257/713, 720; 361/383, 386; 174/52.1, 15.2, 16.3

[56] **References Cited**

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Air-cooled module on p. 1007 of *IBM Technical Disclosure Bulletin* vol. 20, No. 3 Aug. 1977.

Heat removal module on p. 2249 of *IBM Technical Disclosure Bulletin* vol. 22 No. 6 Nov. 1979.

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Attorney, Agent, or Firm—W. G. Fasse; W. F. Fasse

[57] **CLAIM**

The ornamental design for a heat dissipating device for a semiconductor package, as shown and described.

DESCRIPTION

FIG. 1 is a front view of an embodiment of the heat dissipating device for a semiconductor package;

FIG. 2 is a rear view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

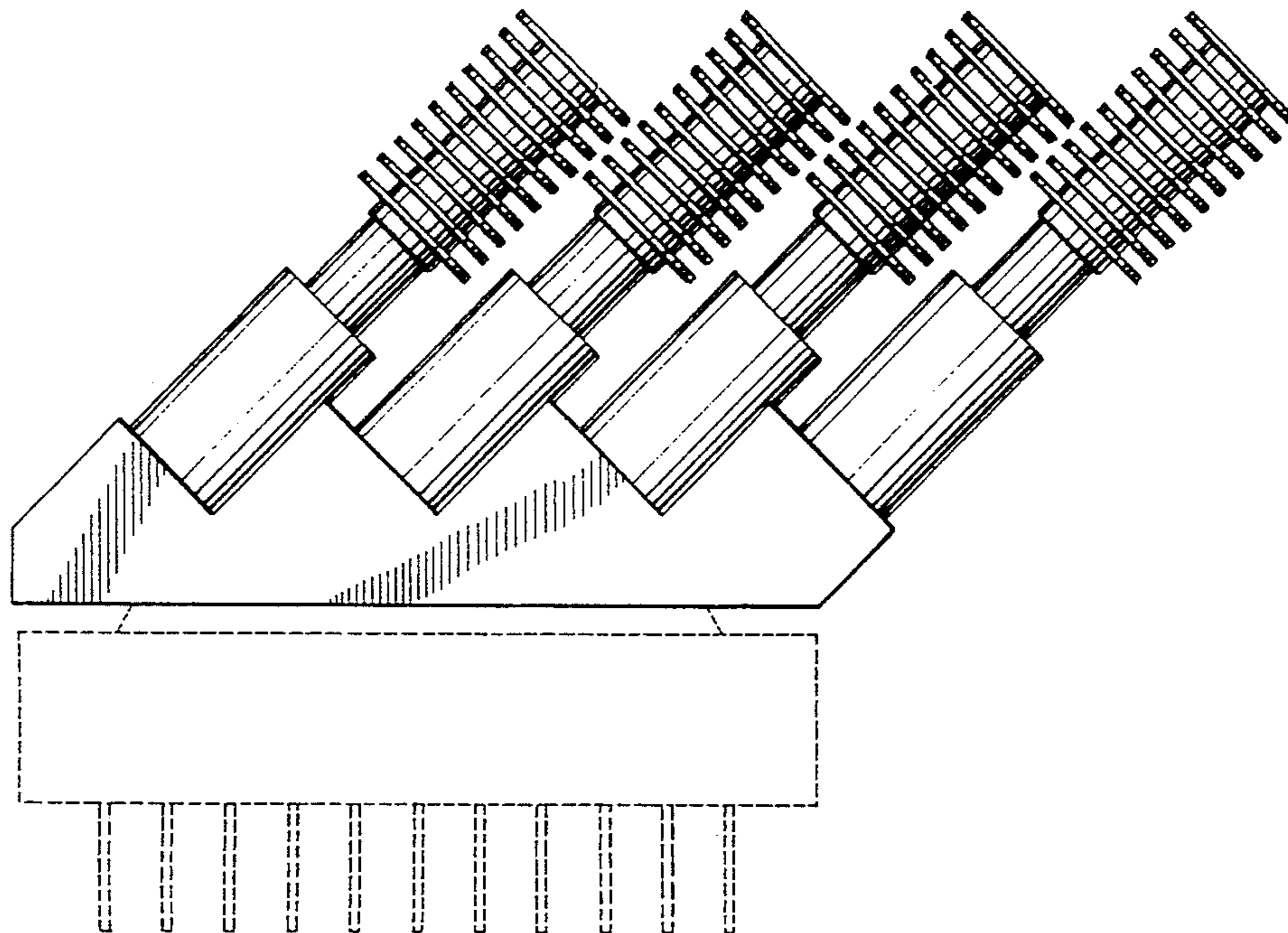
FIG. 5 is a right side view thereof;

FIG. 6 is a perspective view thereof;

FIG. 7 is a sectional view taken along line 7—7 in FIG. 5 with an attached semiconductor package shown in broken lines only since the semiconductor package does not form any part of the claimed design;

FIG. 8 shows the same side view as FIG. 5 with an attached semiconductor package shown in broken lines only since the semiconductor package does not form any part of the claimed design; and,

FIG. 9 is a top view in the direction of the arrow IX seen from a position perpendicular to the top surface of the heat dissipating device for a semiconductor package.



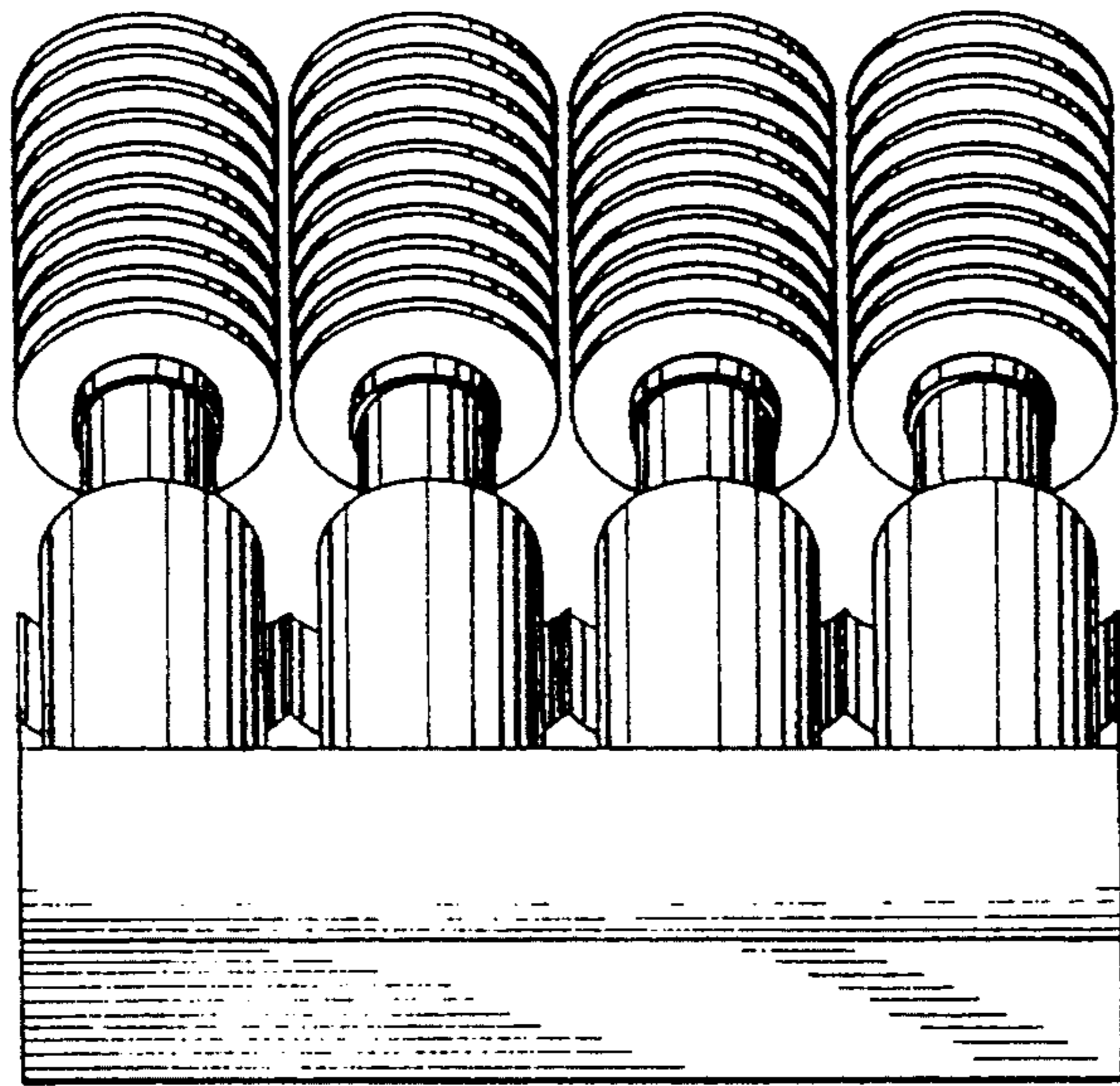


FIG. 1

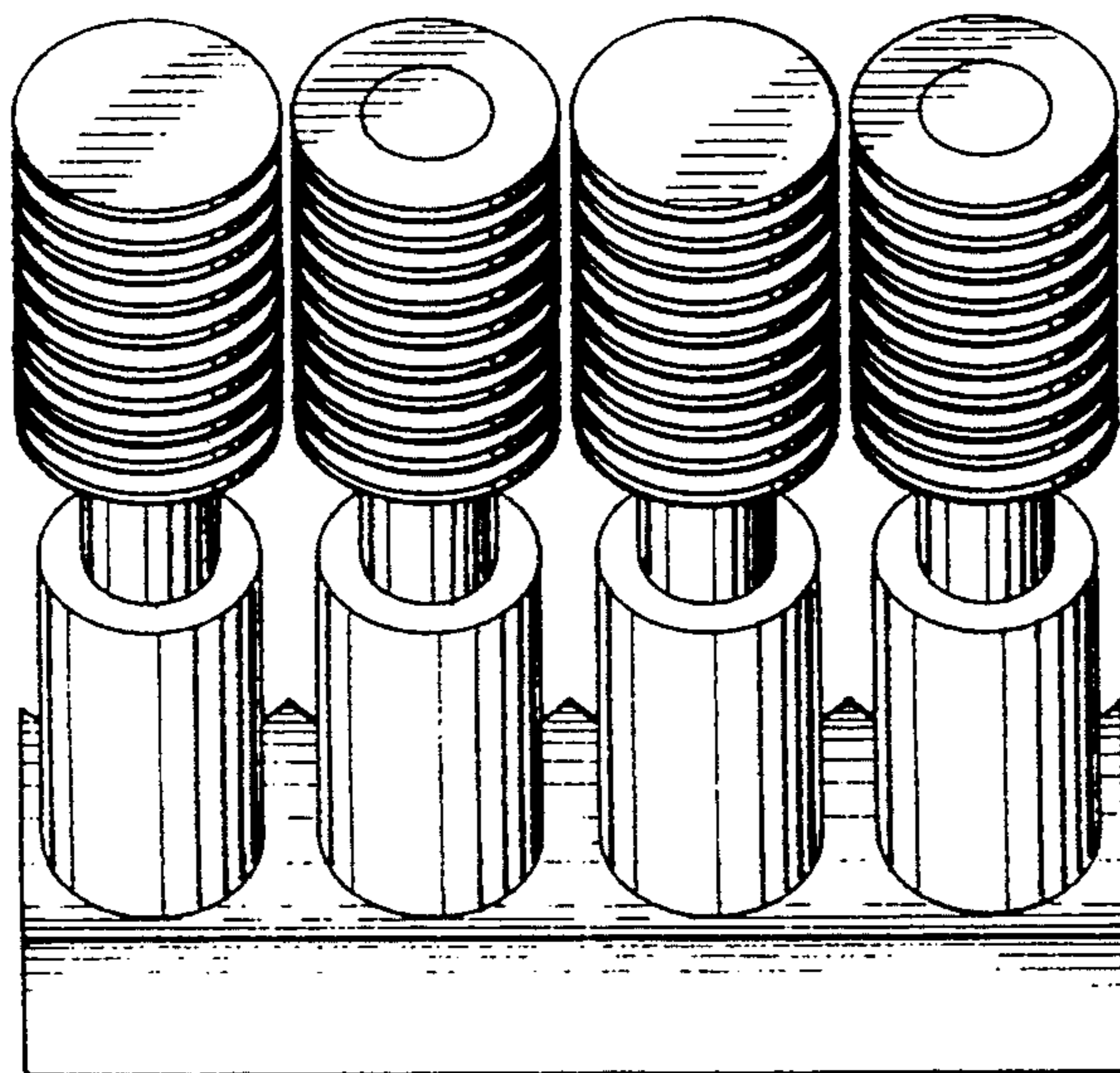


FIG. 2

FIG. 3

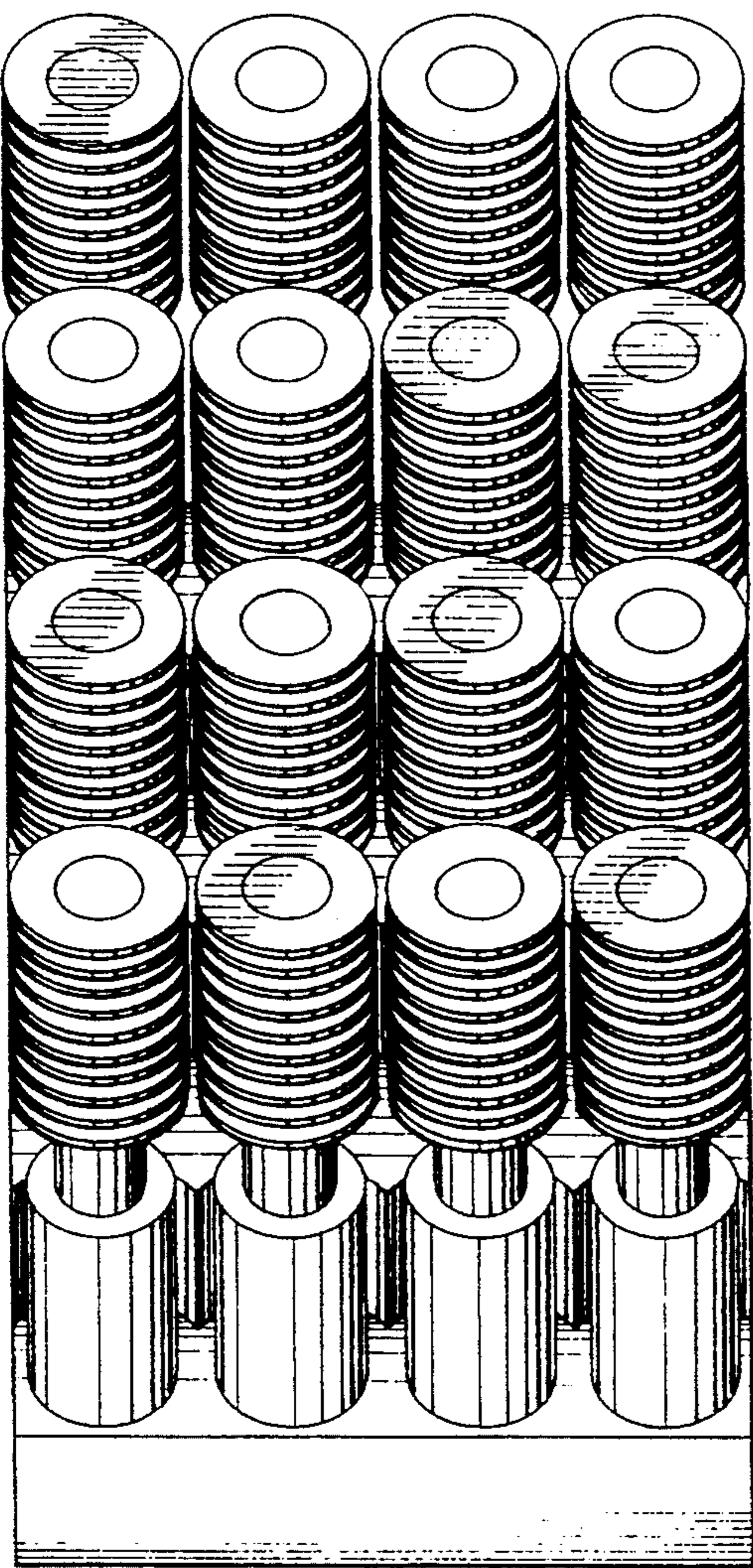
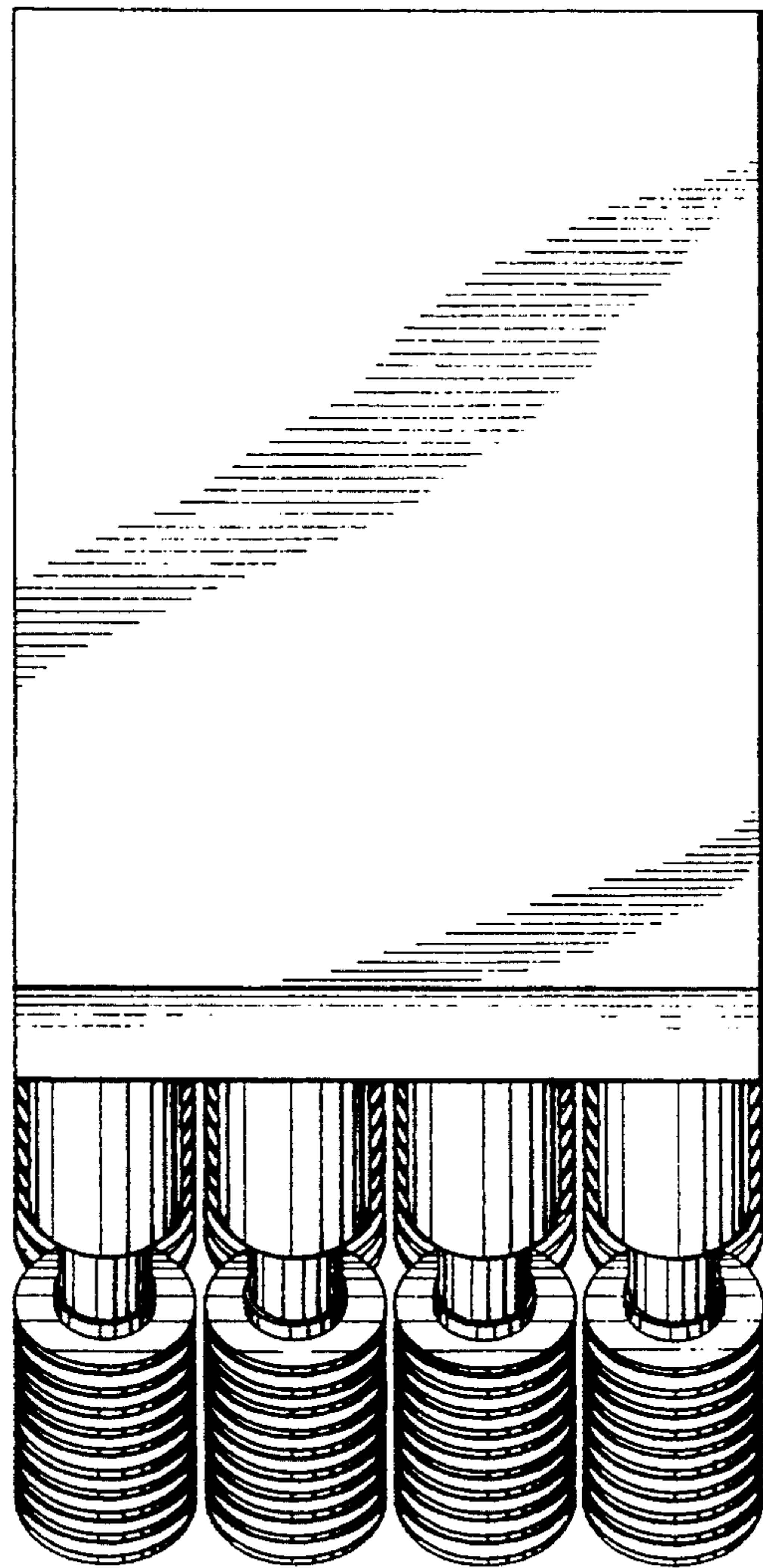


FIG. 4



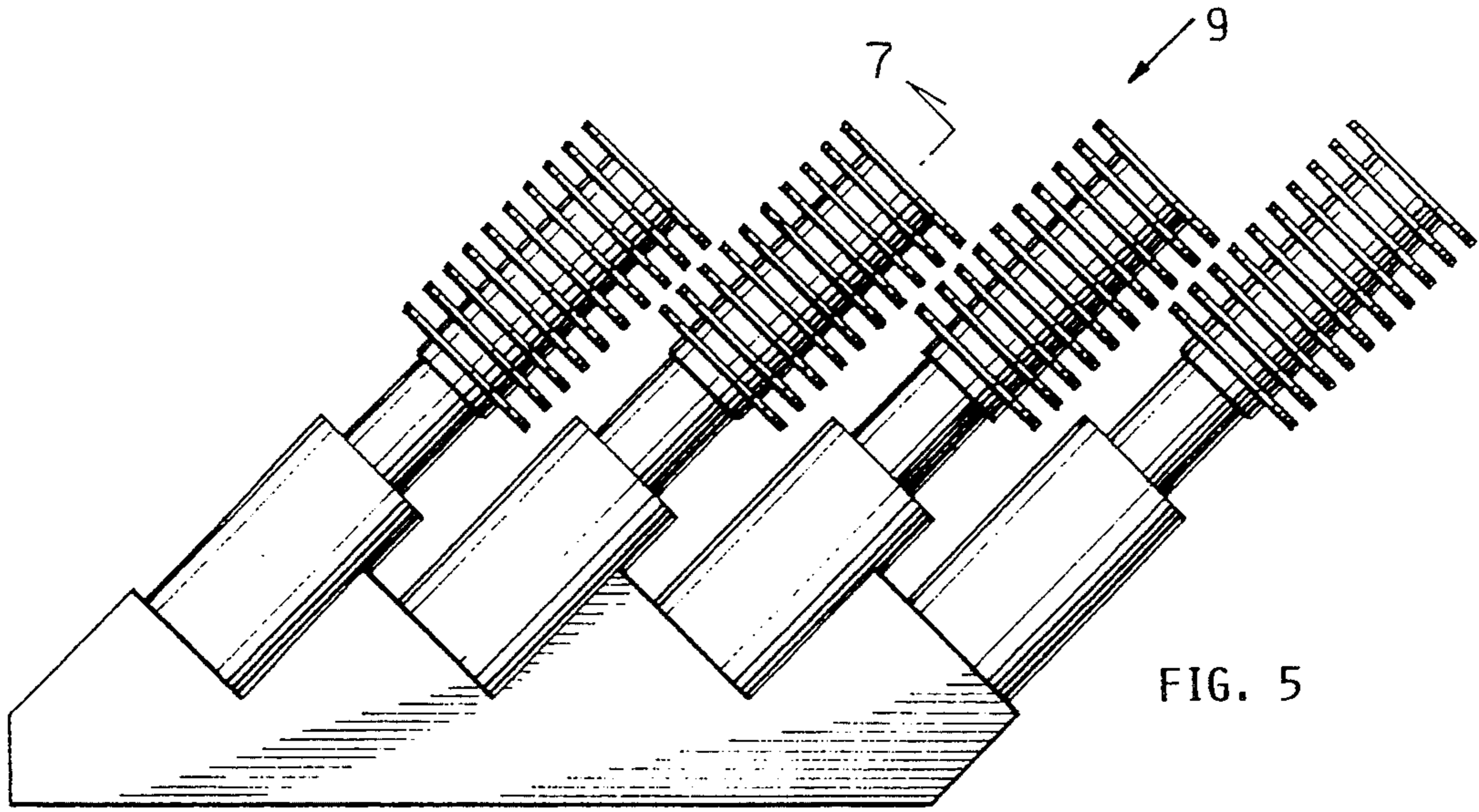


FIG. 5

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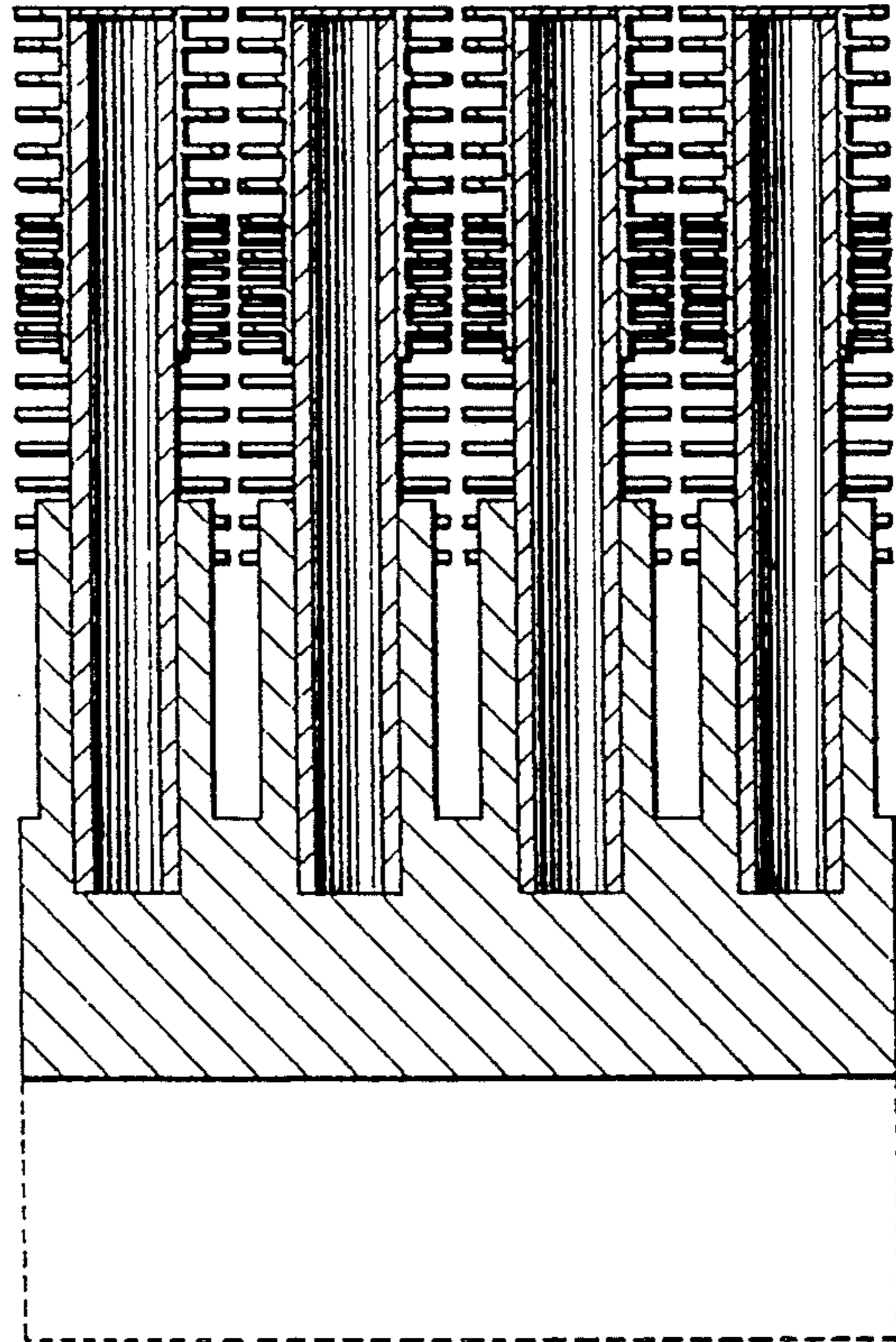


FIG. 7

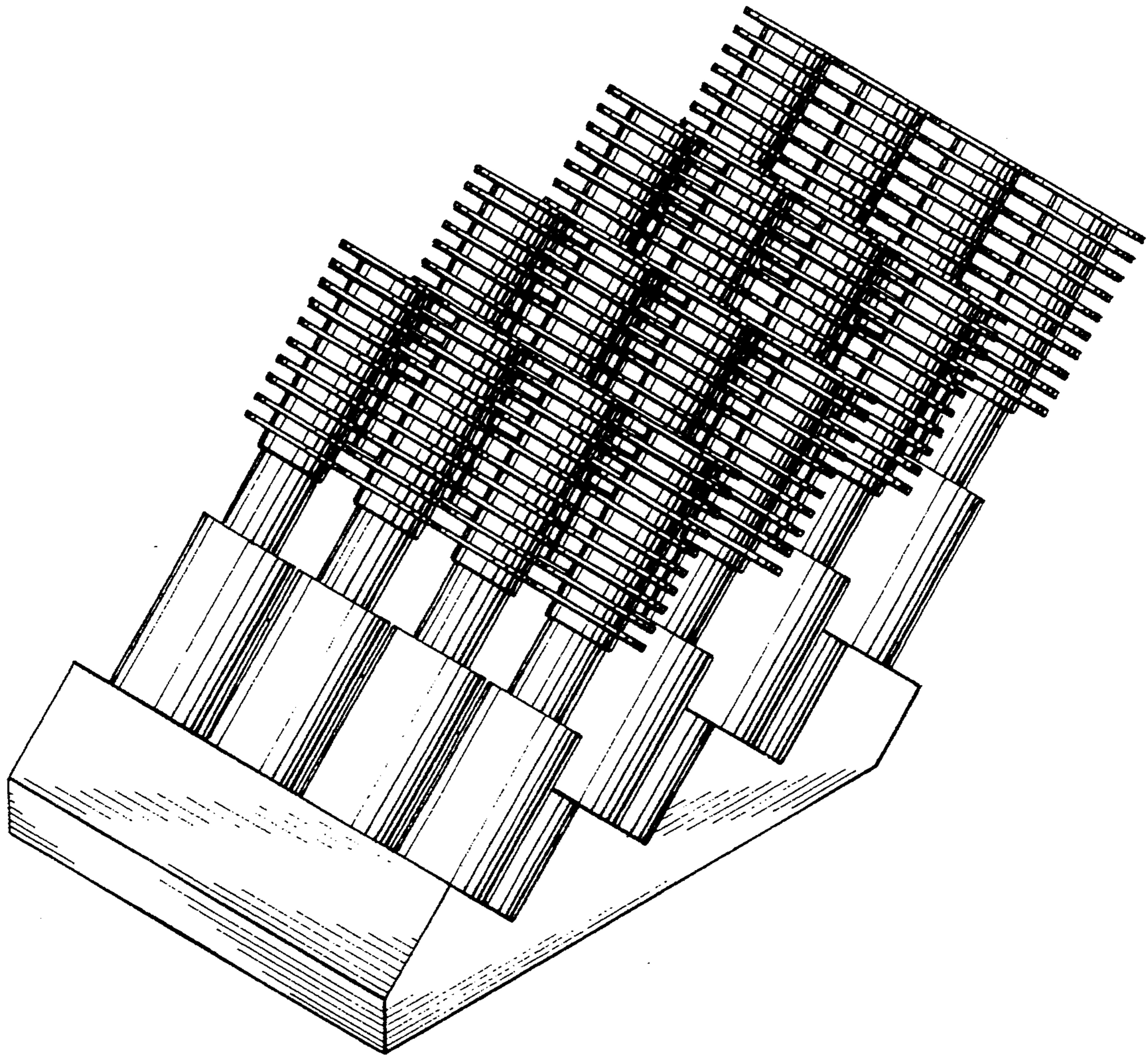


FIG. 6

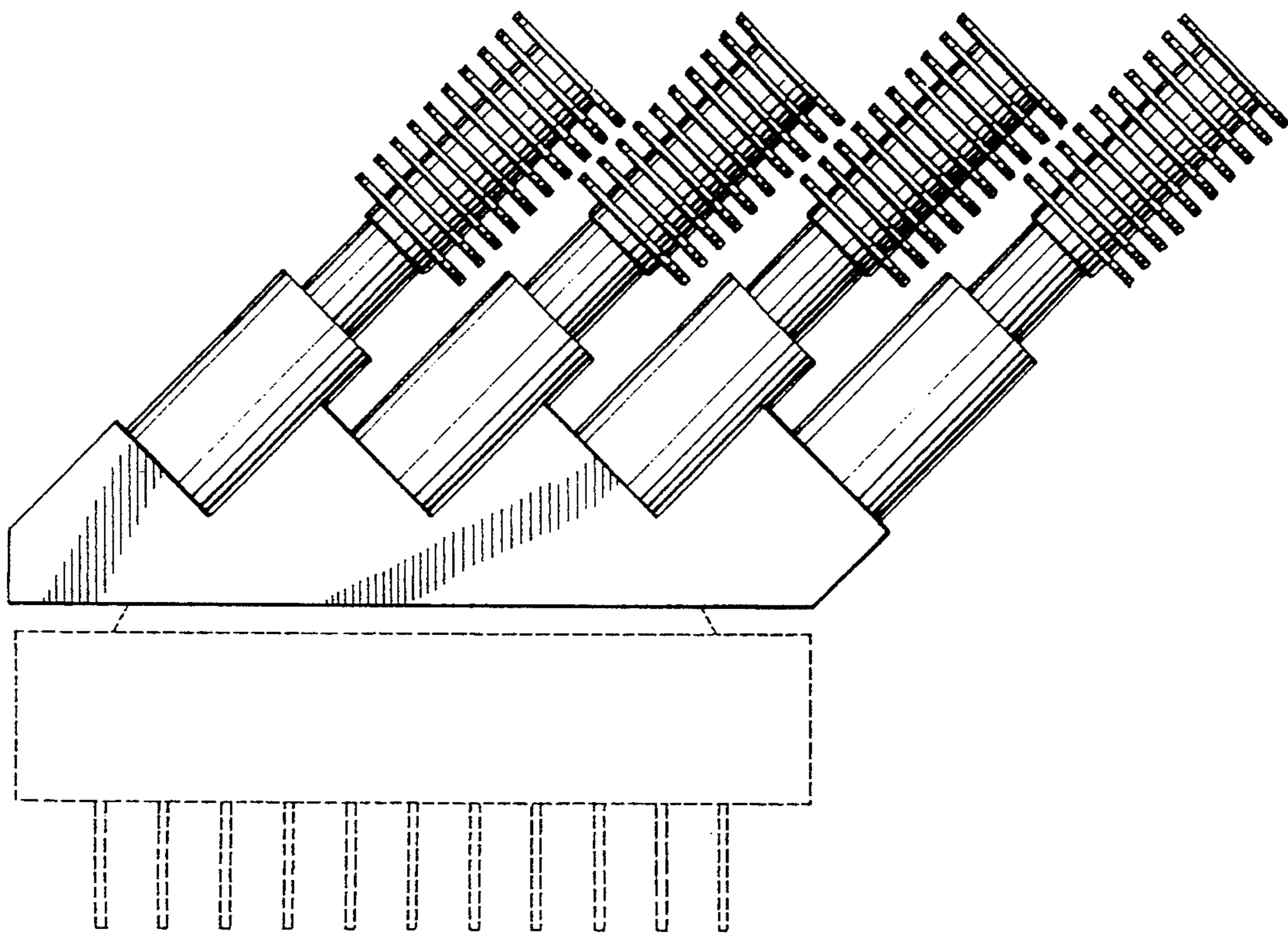


FIG. 8

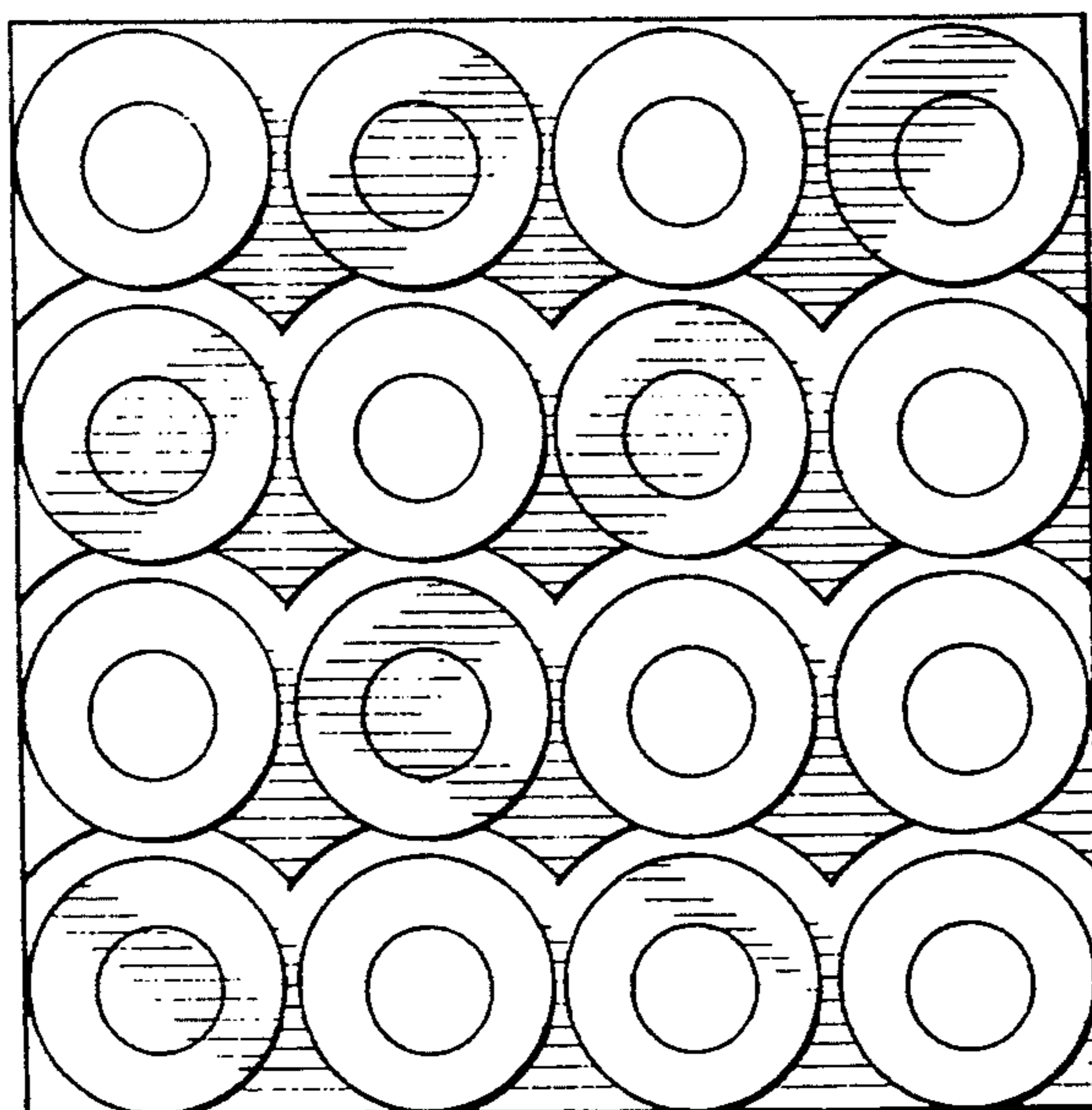


FIG. 9

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : Des. 356,067
DATED : March 7, 1995
INVENTOR(S) : Akira Itoh

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On title page:

Item [63] Related U.S. Application Data:

The present Design Application relates to U. S. Design Application USSN: 07/933,503, filed on: August 21, 1992, now U. S. Design Patent No.: Des. 342,721 which issued on December 28, 1993.--.

Signed and Sealed this
Thirty-first Day of October 1995

Attest:



BRUCE LEHMAN

Attesting Officer

Commissioner of Patents and Trademarks